

### **REMARKS**

Claims 1 and 3-10 are now pending in the application. Applicant amends claims 1, 3 and 5, and adds new claims 9 and 10 herein. Applicant respectfully requests reconsideration and withdrawal of the rejections in view of the amendments and remarks contained herein.

### **CLAIMS 1, 3 AND 5**

Applicant amends claims 1, 3 and 5. Support for the amendment to claim 1 can be found at least in Figs. 2B, 2H and 8E of the original specification. The amendments to claim 3 and 5 more clearly recite that which was previously claimed. No new matter is added.

Claim 1 recites a manufacturing method of a multilayer circuit board, comprising the step of forming at least two wiring layers, an inter-layer insulating film provided between every adjacent two of the wiring layers, and conductive posts for providing electrical conductivity between the wiring layers, wherein: said step includes forming the inter-layer insulating film by using a droplet jetting method after the conductive posts are formed so that the inter-layer insulating film has a flat upper surface, and the upper surfaces of the conductive posts are higher than the upper surface of the inter-layer insulating film.

In accordance with the claimed configuration, the area covered by the inter-layer insulating film can be flat, while the upper surfaces of the conductive posts are higher than the upper surface of the inter-layer insulating film so as to easily connect the wiring layers to each other. The prior art of record fails to teach or suggest such a

configuration. Accordingly, claim 1 and the claims depending therefrom should be in condition for allowance.

#### **NEW CLAIMS**

Applicant adds new claims 9 and 10. Support for the new claims can be found throughout the specification, claims and drawings as originally filed. For example, claim 10 is supported by lines 2 to 4 on page 29 ("preferably, the upper surfaces 18a of the inter-layer conductive posts 18 are slightly higher than the upper surface 23a of the second inter-layer insulating film 23 (by approximately 0.1  $\mu\text{m}$ )"), and Figs. 2H and 8E. Accordingly, no new matter is added.

Claims 9 and 10 depend from claim 1 and should be in condition for allowance for at least the same reasons as set forth above.

#### **CONCLUSION**

It is believed that all of the stated grounds of rejection have been properly traversed, accommodated, or rendered moot. Applicant therefore respectfully requests that the Examiner reconsider and withdraw all presently outstanding rejections. It is believed that a full and complete response has been made to the outstanding Office Action and the present application is in condition for allowance. Thus, prompt and favorable consideration of this amendment is respectfully requested. If the Examiner believes that personal communication will expedite prosecution of this application, the Examiner is invited to telephone the undersigned at (248) 641-1600.

Respectfully submitted,

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